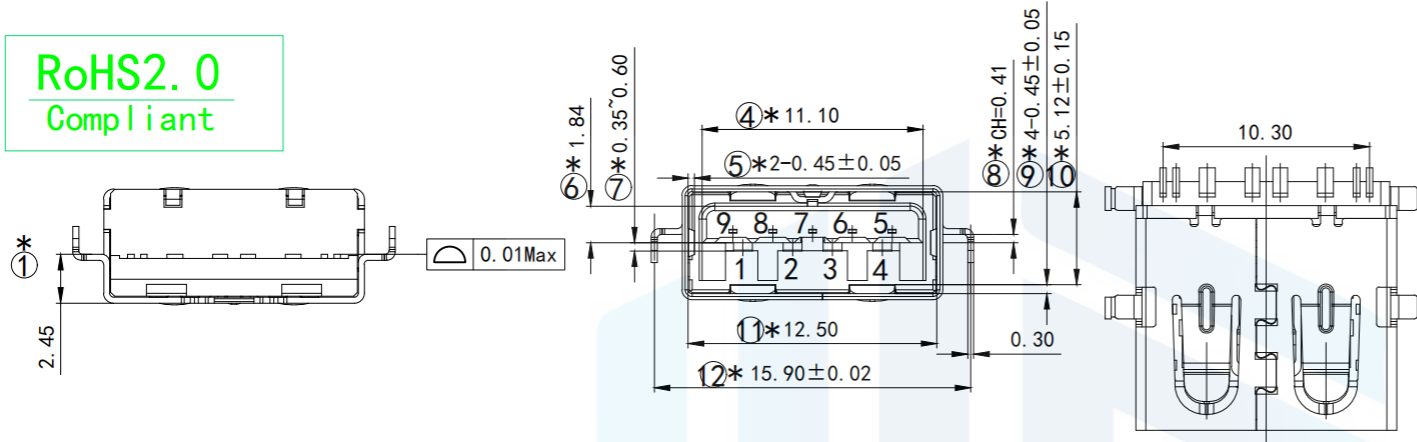
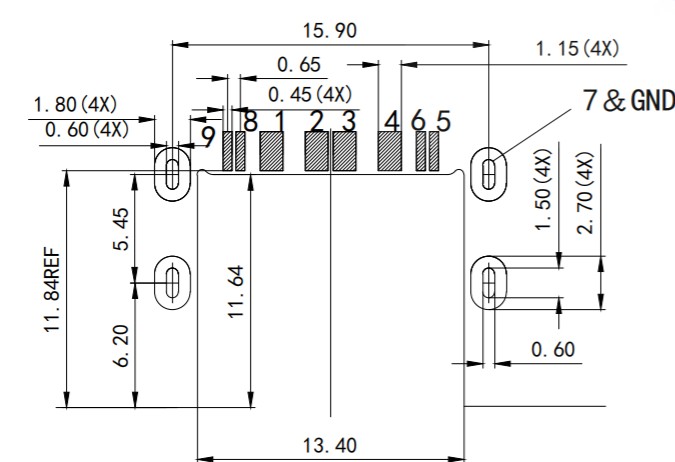
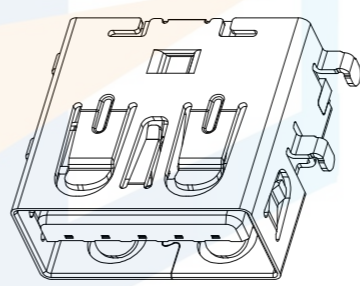
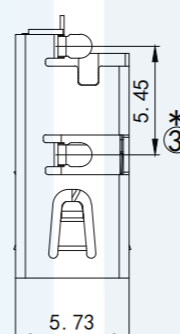
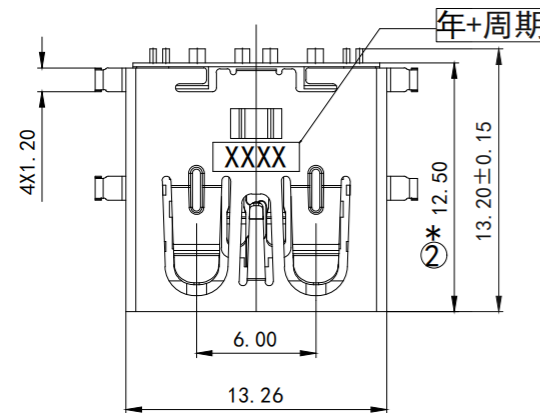



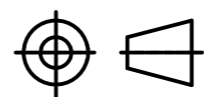
RoHS2.0
Compliant



NOTE:
 1. MATERIAL:
 1.1 INSULATOR:LCP+30%GF, UL94 V-0.
 1.2 CONTACT 1~4PIN: C5191-EH.
 1.3 CONTACT 5~9PIN: C5191-EH.
 1.4 SHELL: SUS304 3/4H
 2. PLATING:
 2.1 CONTACT:CONTACT AREA: GOLD PLATING. SOLDER AREA: 100u" Min MATTE TIN PLATING. UNDER PLATE: 50u" Min NICKEL PLATING. 2.2 SHELL:50u" Min. NICKEL PLATED OVERALL
 3. CHARACTERISTICS:
 3.1 ELECTRICAL CHARACTERISTICS;
 CONTACT RESISTANCE:30mΩ MAXIMUM
 CONTACT CURRENT RATING: 3AV
 R. M. S. DIELECTRIC WITHSTANDING VOLTAGE: 500V
 INSULATION RESISTANCE: 100 MEGOHMS
 MIN OPERATING TEMPERATURE: -25° C~+85° C
 3.2 MECHANICAL: MATING FORCE: 3.57KG Max. UNMATING FORCE: 1.02KG Min.
 4. PART MUST COMPLY ROHS SPECIFICATION
 5. WAVE SOLDER:THE CONNECTOR SHALL BE MOUNTED ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL BE 260+5 C AND IMMERSION DURATION 5 SECONDS.



TOLERANCE: ±0.05, RECOMMENDED PCB LAYOUT (TOP VIEW)

TOLERANCE	X. XXX	±0.05	 东莞市恒祺电子科技有限公司 Dongguan Hengqi Electronic Technology Co., Ltd
	X. XX	±0.15	
PROTECTON	X. X	±0.20	https://www.hq-dz.com phone:15812872448 TITLE: USB3.1 A/F 沉板2.45直边 4定位脚外移(10GB)
	X.	±0.30	
	ANGLE	±5.0°	PART NO: USB3.1-V264
	DRAWN:		DRAWING NO: 13.26*12.5*5.73
	CHECKED:		DATE: 18-10-08
	APPROVED:		DATE: 18-10-08
			UNIT: mm
			SCALE: FULL
			SIZE: A4